



#5/B

Our Docket No.: M4065.0184/P184-A
Micron Docket No.: 99-0132/US

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Alan G. Wood et al.

Serial No.: 09/930,295

Group Art Unit: 2815

Filed: August 16, 2001

Examiner: C. Chu

For: SEMICONDUCTOR DEVICE
PACKAGE AND METHOD

AMENDMENT

Box Non-Fee Amendment
Commissioner for Patents
Washington, DC 20231

RECEIVED
MAR 20 2002
TECHNOLOGY CENTER 2800

Dear Sir:

In response to the Office Action dated December 14, 2001 (Paper No.4),
please amend the above-identified U.S. Patent application as follows:

In the Specification:

Please replace the respective paragraphs of the specification with the amended
paragraphs below:

Page 5, the paragraph beginning at line 20 through line 28:

B1 Referring now to the drawings, where like reference numerals designate like
elements, there is shown in FIG. 1 a semiconductor device package 10 constructed in